



EIPC SPEeDNEWS

The Weekly On-Line Newsletter from the European Institute of Printed Circuits.
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NEWS FROM THE EIPC

Two new members for EIPC

EIPC is pleased to advise that we have two new companies who have joined us in the last few days.

They are:

1. Technolam, Froisdorf, Germany

Contact person: Mr. Günther Fuchs and Mr. Andreas Folge

Phone: +49-2241-8737-0

Website: www.technolam.de

2. HDP User Group International Inc., Cave Creek, USA

Contact person: Mr. Marshall Andrews and Mr. Larry Marcanti

Phone: +1-512-258-0332

Website: www.hdpug.org

High Density Packaging (HDP) User Group is a global research and development organization based in Cave Creek Arizona, USA dedicated to “reducing the costs and risks for the Electronics Manufacturing industry when using advanced electronic packaging and assembly”. This international industry led group organizes and conducts R&D programs to address the technical issues facing the industry, including design, printed circuit board manufacturing, electronics assembly, and environmental compliance. Membership is open to all companies throughout the world who use, supply, or support electronics manufacturing.



HDP User Group Member Company Representatives at a recent Member Project Review Meeting.

Collaborative leverage is one of the keys to HDP User Group's success. Our projects provide extraordinary cost savings for our membership by employing shared resources directed at key issues or new technologies our membership wishes to address.

HDP User Group has been a project oriented industry consortium for over 20 years. In addressing the integration of new electronics component packaging and interconnect technologies into company supply chains, it continues to provide value to all its 51 member companies.

HDP User Group maintains additional offices in Austin, Texas, The UK, and Singapore.

EIPC-EFRA-CEFIC Workshop

In conjunction with CEFIC and EFRA (the European Flame Retardants Association), EIPC are pleased to announce that they will be holding a half-day workshop (10:00-14:00 h.) on Wednesday 23rd September 2015 at the Cefic - European Chemical Industry Council in Brussels, Belgium.

Flame retardants find use in many segments of the electronics industry; all of which provide protection from fire hazards to improve user safety.

During this workshop you will learn about the following topics;

- EU Legislative framework, RoHS REACH and WEEE and End of Life
- Possible impact of EU legislation on future PCB manufacture in Europe
- Legislative status of TBBPA, the most widely used flame retardant in PCBs

The speakers will include Alun Morgan, Chairman EIPC, Professor Martin Goosey, VP Technology EIPC who will be accompanied by Mr. L. Tange of ICL.

Workshop agenda:

- Introduction EFRA
- Overview on Legislation - Prof. M. Goosey
- Flame retardant use in PCB Base Materials - A. Morgan
- Lunch
- RoHS 2, current status and future impact - F.Kohl
- Recycling, end of life - L. Tange
- REACH process for end users - EFRA
- Panel Q&A

Workshop fee:

EIPC Members / EFRA members: € 200.-

Non-members: € 300.-

Additional employee from the same company 20% discount: € 160.- /
€ 240

You can download the registration form at www.eipc.org

In case of any questions please feel free to contact the EIPC office at eipc@eipc.org or +31-43-3440872.